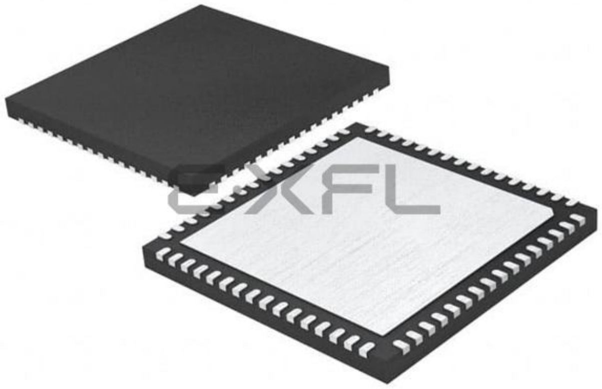


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

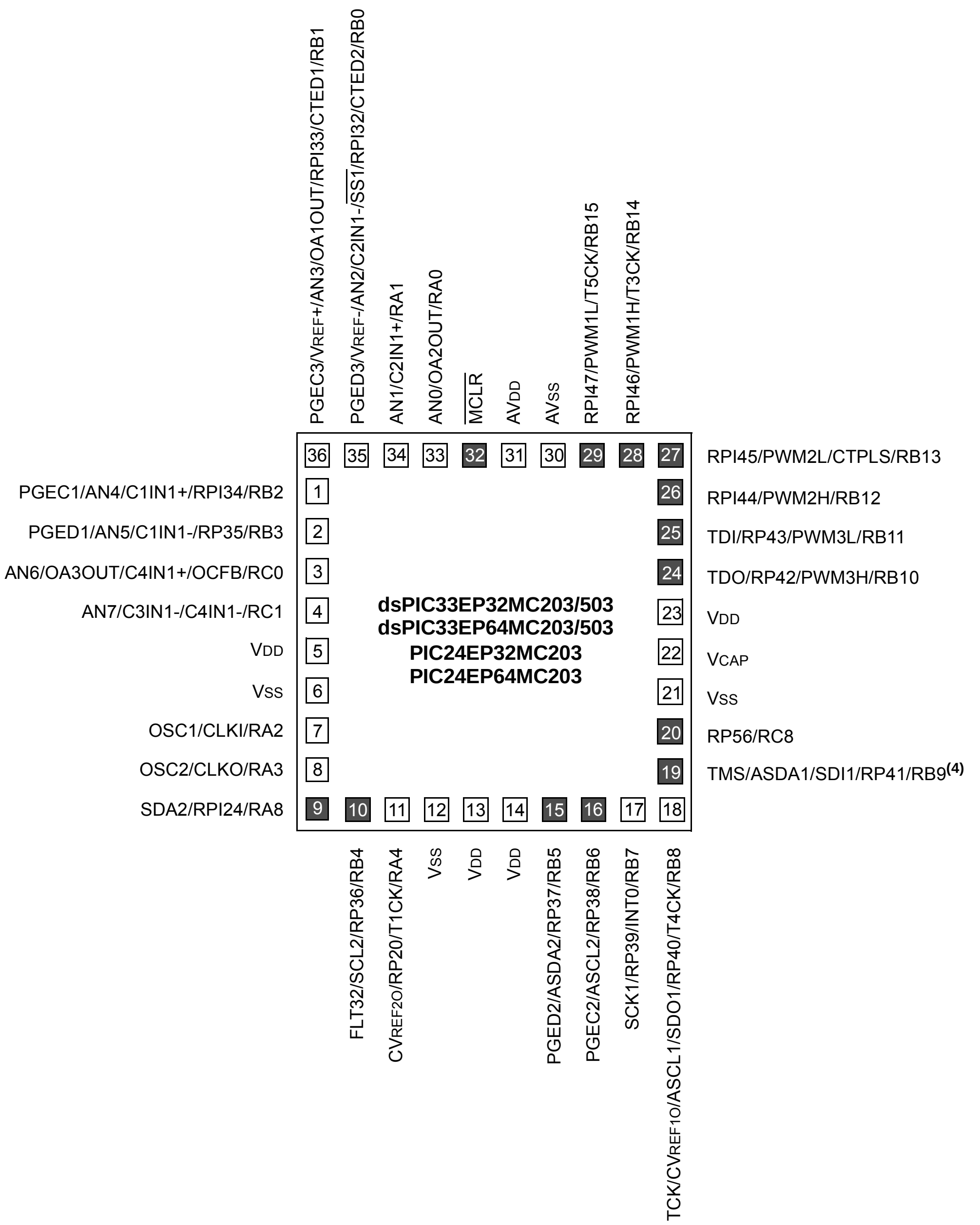
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep64mc506t-e-mr

Pin Diagrams (Continued)

36-Pin VTLA[1,2,3]

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name[4]	Pin Type	Buffer Type	PPS	Description
AN0-AN15	I	Analog	No	Analog input channels.
CLKI	I	ST/ CMOS	No	External clock source input. Always associated with OSC1 pin function.
CLKO	O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1 OSC2	I I/O	ST/ CMOS —	No No	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise. Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
REFCLKO	O	—	Yes	Reference clock output.
IC1-IC4	I	ST	Yes	Capture Inputs 1 through 4.
OCFA OCFB OC1-OC4	I I O	ST ST —	Yes No Yes	Compare Fault A input (for Compare channels). Compare Fault B input (for Compare channels). Compare Outputs 1 through 4.
INT0 INT1 INT2	I I I	ST ST ST	No Yes Yes	External Interrupt 0. External Interrupt 1. External Interrupt 2.
RA0-RA4, RA7-RA12	I/O	ST	No	PORTA is a bidirectional I/O port.
RB0-RB15	I/O	ST	No	PORTB is a bidirectional I/O port.
RC0-RC13, RC15	I/O	ST	No	PORTC is a bidirectional I/O port.
RD5, RD6, RD8	I/O	ST	No	PORTD is a bidirectional I/O port.
RE12-RE15	I/O	ST	No	PORTE is a bidirectional I/O port.
RF0, RF1	I/O	ST	No	PORTF is a bidirectional I/O port.
RG6-RG9	I/O	ST	No	PORTG is a bidirectional I/O port.
T1CK T2CK T3CK T4CK T5CK	I I I I I	ST ST ST ST ST	No Yes No No No	Timer1 external clock input. Timer2 external clock input. Timer3 external clock input. Timer4 external clock input. Timer5 external clock input.
CTPLS CTED1 CTED2	O I I	ST ST ST	No No No	CTMU pulse output. CTMU External Edge Input 1. CTMU External Edge Input 2.
$\overline{\text{U1CTS}}$ $\overline{\text{U1RTS}}$ U1RX U1TX BCLK1	I O I O O	ST — ST — ST	No No Yes Yes No	UART1 Clear-To-Send. UART1 Ready-To-Send. UART1 receive. UART1 transmit. UART1 IrDA® baud clock output.

Legend:

CMOS = CMOS compatible input or output	Analog = Analog input	P = Power
ST = Schmitt Trigger input with CMOS levels	O = Output	I = Input
PPS = Peripheral Pin Select	TTL = TTL input buffer	

Note 1: This pin is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: This pin is available on dsPIC33EPXXXGP/MC50X devices only.

3: This is the default Fault on Reset for dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices. See **Section 16.0 "High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"** for more information.

4: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

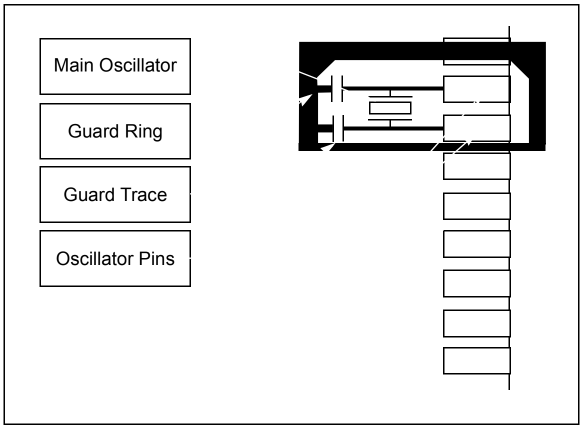
- *"Using MPLAB® ICD 3"* (poster) DS51765
- *"MPLAB® ICD 3 Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™ In-Circuit Emulator"* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency Primary Oscillator and a low-frequency Secondary Oscillator. For details, see **Section 9.0 "Oscillator Configuration"** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"CPU"** (DS70359) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for digital signal processing. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space.

An instruction prefetch mechanism helps maintain throughput and provides predictable execution. Most instructions execute in a single-cycle effective execution rate, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction, PSV accesses and the table instructions. Overhead-free program loop constructs are supported using the `DO` and `REPEAT` instructions, both of which are interruptible at any point.

3.1 Registers

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices have sixteen, 16-bit working registers in the programmer's model. Each of the working registers can act as a data, address or address offset register. The 16th working register (W15) operates as a Software Stack Pointer for interrupts and calls.

3.2 Instruction Set

The instruction set for dsPIC33EPXXXGP50X and dsPIC33EPXXXMC20X/50X devices has two classes of instructions: the MCU class of instructions and the DSP class of instructions. The instruction set for PIC24EPXXXGP/MC20X devices has the MCU class of instructions only and does not support DSP instructions. These two instruction classes are seamlessly integrated into the architecture and execute from a single execution unit. The instruction set includes many addressing modes and was designed for optimum C compiler efficiency.

3.3 Data Space Addressing

The base Data Space can be addressed as 64 Kbytes (32K words).

The Data Space includes two ranges of memory, referred to as X and Y data memory. Each memory range is accessible through its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear Data Space. On dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y Data Spaces have memory locations that are device-specific, and are described further in the data memory maps in **Section 4.2 "Data Address Space"**.

The upper 32 Kbytes of the Data Space memory map can optionally be mapped into Program Space (PS) at any 32-Kbyte aligned program word boundary. The Program-to-Data Space mapping feature, known as Program Space Visibility (PSV), lets any instruction access Program Space as if it were Data Space. Moreover, the Base Data Space address is used in conjunction with a Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space (EDS) address. The EDS can be addressed as 8M words or 16 Mbytes. Refer to the **"Data Memory"** (DS70595) and **"Program Memory"** (DS70613) sections in the *"dsPIC33/PIC24 Family Reference Manual"* for more details on EDS, PSV and table accesses.

On the dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, overhead-free circular buffers (Modulo Addressing) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. The X AGU Circular Addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data re-ordering for radix-2 FFT algorithms. PIC24EPXXXGP/MC20X devices do not support Modulo and Bit-Reversed Addressing.

3.4 Addressing Modes

The CPU supports these addressing modes:

- Inherent (no operand)
- Relative
- Literal
- Memory Direct
- Register Direct
- Register Indirect

Each instruction is associated with a predefined addressing mode group, depending upon its functional requirements. As many as six addressing modes are supported for each instruction.

4.6.3 MODULO ADDRESSING APPLICABILITY

Modulo Addressing can be applied to the Effective Address (EA) calculation associated with any W register. Address boundaries check for addresses equal to:

- The upper boundary addresses for incrementing buffers
- The lower boundary addresses for decrementing buffers

It is important to realize that the address boundaries check for addresses less than, or greater than, the upper (for incrementing buffers) and lower (for decrementing buffers) boundary addresses (not just equal to). Address changes can, therefore, jump beyond boundaries and still be adjusted correctly.

Note: The modulo corrected Effective Address is written back to the register only when Pre-Modify or Post-Modify Addressing mode is used to compute the Effective Address. When an address offset (such as [W7 + W2]) is used, Modulo Addressing correction is performed but the contents of the register remain unchanged.

4.7 Bit-Reversed Addressing (dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X Devices Only)

Bit-Reversed Addressing mode is intended to simplify data reordering for radix-2 FFT algorithms. It is supported by the X AGU for data writes only.

The modifier, which can be a constant value or register contents, is regarded as having its bit order reversed. The address source and destination are kept in normal order. Thus, the only operand requiring reversal is the modifier.

4.7.1 BIT-REVERSED ADDRESSING IMPLEMENTATION

Bit-Reversed Addressing mode is enabled when all these conditions are met:

- BWMx bits (W register selection) in the MODCON register are any value other than ‘`1111`’ (the stack cannot be accessed using Bit-Reversed Addressing)
- The BREN bit is set in the XBREV register
- The addressing mode used is Register Indirect with Pre-Increment or Post-Increment

If the length of a bit-reversed buffer is $M = 2^N$ bytes, the last ‘N’ bits of the data buffer start address must be zeros.

XBREV<14:0> is the Bit-Reversed Addressing modifier, or ‘pivot point’, which is typically a constant. In the case of an FFT computation, its value is equal to half of the FFT data buffer size.

Note: All bit-reversed EA calculations assume word-sized data (LSb of every EA is always clear). The XBREVx value is scaled accordingly to generate compatible (byte) addresses.

When enabled, Bit-Reversed Addressing is executed only for Register Indirect with Pre-Increment or Post-Increment Addressing and word-sized data writes. It does not function for any other addressing mode or for byte-sized data and normal addresses are generated instead. When Bit-Reversed Addressing is active, the W Address Pointer is always added to the address modifier (XBREVx) and the offset associated with the Register Indirect Addressing mode is ignored. In addition, as word-sized data is a requirement, the LSb of the EA is ignored (and always clear).

Note: Modulo Addressing and Bit-Reversed Addressing can be enabled simultaneously using the same W register, but Bit-Reversed Addressing operation will always take precedence for data writes when enabled.

If Bit-Reversed Addressing has already been enabled by setting the BREN (XBREV<15>) bit, a write to the XBREV register should not be immediately followed by an indirect read operation using the W register that has been designated as the Bit-Reversed Pointer.

8.0 DIRECT MEMORY ACCESS (DMA)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **“Direct Memory Access (DMA)”** (DS70348) in the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The DMA Controller transfers data between Peripheral Data registers and Data Space SRAM

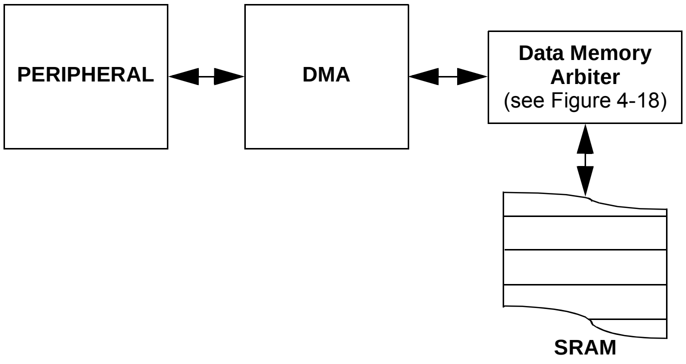
In addition, DMA can access the entire data memory space. The Data Memory Bus Arbiter is utilized when either the CPU or DMA attempts to access SRAM, resulting in potential DMA or CPU stalls.

The DMA Controller supports 4 independent channels. Each channel can be configured for transfers to or from selected peripherals. Some of the peripherals supported by the DMA Controller include:

- ECAN™
- Analog-to-Digital Converter (ADC)
- Serial Peripheral Interface (SPI)
- UART
- Input Capture
- Output Compare

Refer to Table 8-1 for a complete list of supported peripherals.

FIGURE 8-1: DMA CONTROLLER MODULE



REGISTER 8-12: DMARQC: DMA REQUEST COLLISION STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	RQCOL3	RQCOL2	RQCOL1	RQCOL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3 **RQCOL3:** DMA Channel 3 Transfer Request Collision Flag bit
1 = User force and interrupt-based request collision is detected
0 = No request collision is detected

bit 2 **RQCOL2:** DMA Channel 2 Transfer Request Collision Flag bit
1 = User force and interrupt-based request collision is detected
0 = No request collision is detected

bit 1 **RQCOL1:** DMA Channel 1 Transfer Request Collision Flag bit
1 = User force and interrupt-based request collision is detected
0 = No request collision is detected

bit 0 **RQCOL0:** DMA Channel 0 Transfer Request Collision Flag bit
1 = User force and interrupt-based request collision is detected
0 = No request collision is detected

15.0 OUTPUT COMPARE

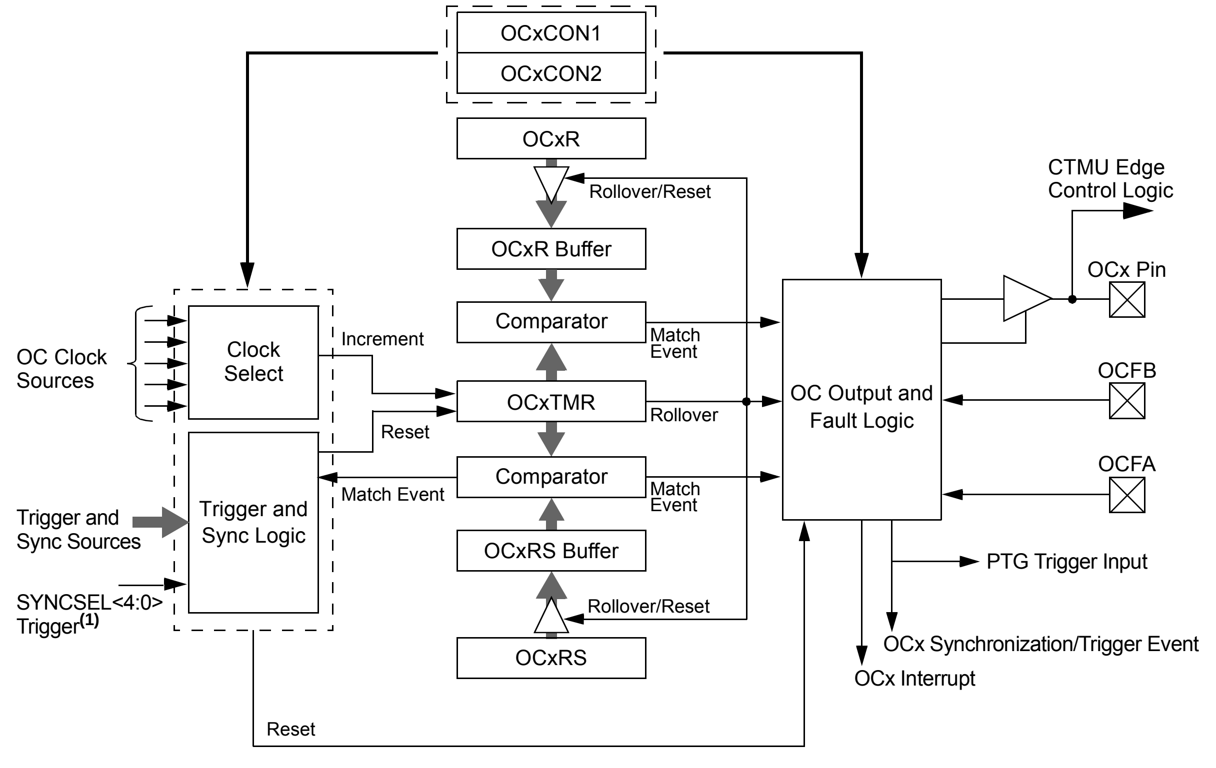
Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Output Compare"** (DS70358) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The output compare module can select one of seven available clock sources for its time base. The module compares the value of the timer with the value of one or two compare registers depending on the operating mode selected. The state of the output pin changes when the timer value matches the compare register value. The output compare module generates either a single output pulse or a sequence of output pulses, by changing the state of the output pin on the compare match events. The output compare module can also generate interrupts on compare match events and trigger DMA data transfers.

Note: See **"Output Compare"** (DS70358) in the *"dsPIC33/PIC24 Family Reference Manual"* for OCxR and OCxRS register restrictions.

FIGURE 15-1: OUTPUT COMPARE x MODULE BLOCK DIAGRAM



Note 1: The Trigger/Sync source is enabled by default and is set to Timer2 as a source. This timer must be enabled for proper OCx module operation or the Trigger/Sync source must be changed to another source option.

REGISTER 16-7: PWMCONx: PWMx CONTROL REGISTER (CONTINUED)

bit 7-6 **DTC<1:0>:** Dead-Time Control bits

11 = Dead-Time Compensation mode
10 = Dead-time function is disabled
01 = Negative dead time is actively applied for Complementary Output mode
00 = Positive dead time is actively applied for all output modes

bit 5 **DTCP:** Dead-Time Compensation Polarity bit[3]

When Set to '1':
If DTCMPx = 0, PWMxL is shortened and PWMxH is lengthened.
If DTCMPx = 1, PWMxH is shortened and PWMxL is lengthened.

When Set to '0':
If DTCMPx = 0, PWMxH is shortened and PWMxL is lengthened.
If DTCMPx = 1, PWMxL is shortened and PWMxH is lengthened.

bit 4 **Unimplemented:** Read as '0'

bit 3 **MTBS:** Master Time Base Select bit

1 = PWM generator uses the secondary master time base for synchronization and as the clock source for the PWM generation logic (if secondary time base is available)
0 = PWM generator uses the primary master time base for synchronization and as the clock source for the PWM generation logic

bit 2 **CAM:** Center-Aligned Mode Enable bit[2,4]

1 = Center-Aligned mode is enabled
0 = Edge-Aligned mode is enabled

bit 1 **XPRES:** External PWMx Reset Control bit[5]

1 = Current-limit source resets the time base for this PWM generator if it is in Independent Time Base mode
0 = External pins do not affect PWMx time base

bit 0 **IUE:** Immediate Update Enable bit[2]

1 = Updates to the active MDC/PDCx/DTRx/ALTDTRx/PHASEx registers are immediate
0 = Updates to the active MDC/PDCx/DTRx/ALTDTRx/PHASEx registers are synchronized to the PWMx period boundary

Note 1: Software must clear the interrupt status here and in the corresponding IFSx bit in the interrupt controller.
2: These bits should not be changed after the PWMx is enabled (PTEN = 1).
3: DTC<1:0> = 11 for DTCP to be effective; otherwise, DTCP is ignored.
4: The Independent Time Base (ITB = 1) mode must be enabled to use Center-Aligned mode. If ITB = 0, the CAM bit is ignored.
5: To operate in External Period Reset mode, the ITB bit must be '1' and the CLMOD bit in the FCLCONx register must be '0'.

REGISTER 21-7: CxINTE: ECANx INTERRUPT ENABLE REGISTER

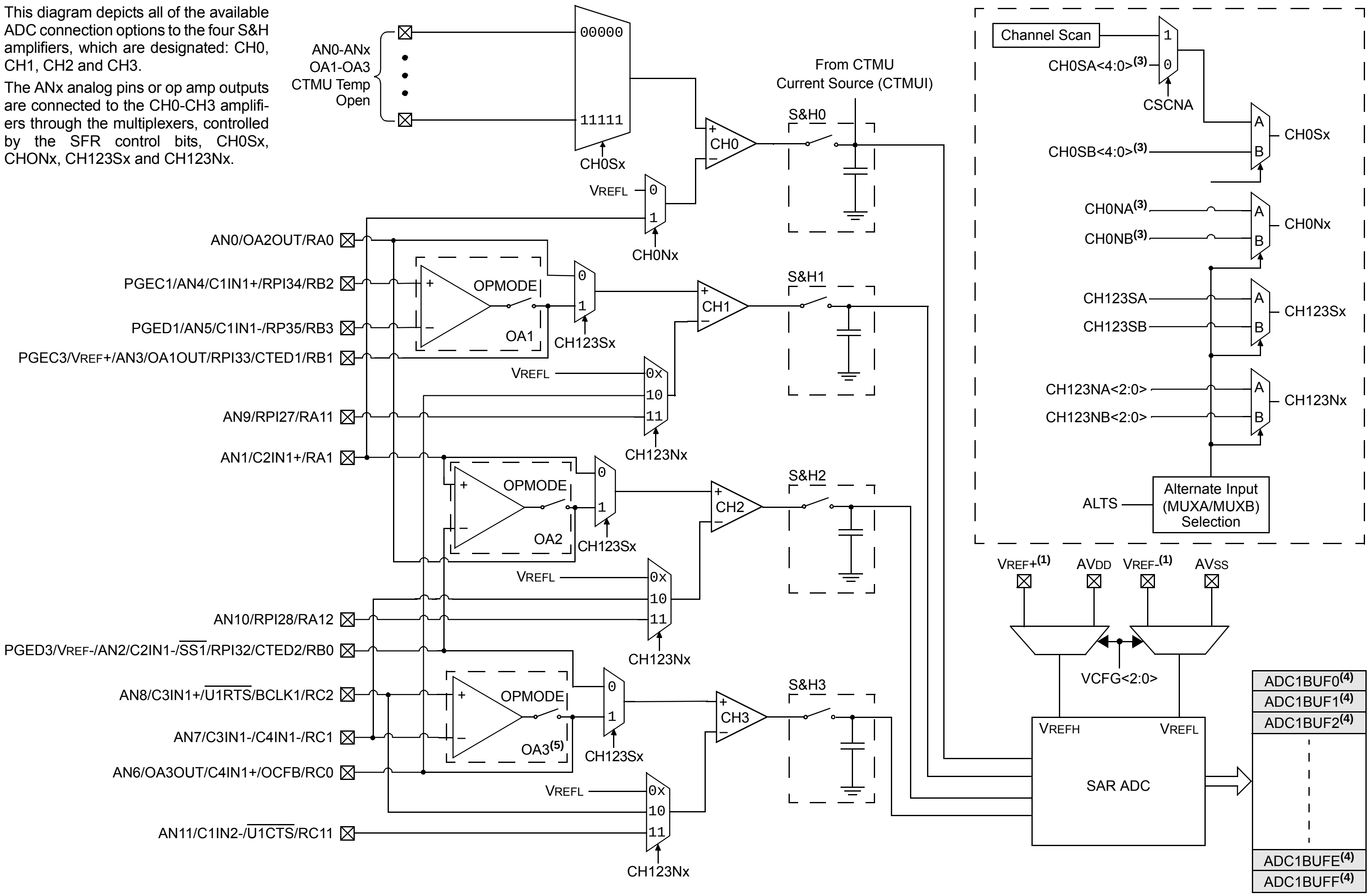
U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
IVRIE	WAKIE	ERRIE	—	FIFOIE	RBOVIE	RBIE	TBIE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8	**Unimplemented:** Read as ‘0’
bit 7	**IVRIE:** Invalid Message Interrupt Enable bit 1 = Interrupt request is enabled 0 = Interrupt request is not enabled
bit 6	**WAKIE:** Bus Wake-up Activity Interrupt Enable bit 1 = Interrupt request is enabled 0 = Interrupt request is not enabled
bit 5	**ERRIE:** Error Interrupt Enable bit 1 = Interrupt request is enabled 0 = Interrupt request is not enabled
bit 4	**Unimplemented:** Read as ‘0’
bit 3	**FIFOIE:** FIFO Almost Full Interrupt Enable bit 1 = Interrupt request is enabled 0 = Interrupt request is not enabled
bit 2	**RBOVIE:** RX Buffer Overflow Interrupt Enable bit 1 = Interrupt request is enabled 0 = Interrupt request is not enabled
bit 1	**RBIE:** RX Buffer Interrupt Enable bit 1 = Interrupt request is enabled 0 = Interrupt request is not enabled
bit 0	**TBIE:** TX Buffer Interrupt Enable bit 1 = Interrupt request is enabled 0 = Interrupt request is not enabled

FIGURE 23-1: ADC MODULE BLOCK DIAGRAM WITH CONNECTION OPTIONS FOR ANx PINS AND OP AMPS



This diagram depicts all of the available ADC connection options to the four S&H amplifiers, which are designated: CH0, CH1, CH2 and CH3.

The ANx analog pins or op amp outputs are connected to the CH0-CH3 amplifiers through the multiplexers, controlled by the SFR control bits, CH0Sx, CHONx, CH123Sx and CH123Nx.

Note 1: VREF+, VREF- inputs can be multiplexed with other analog inputs.

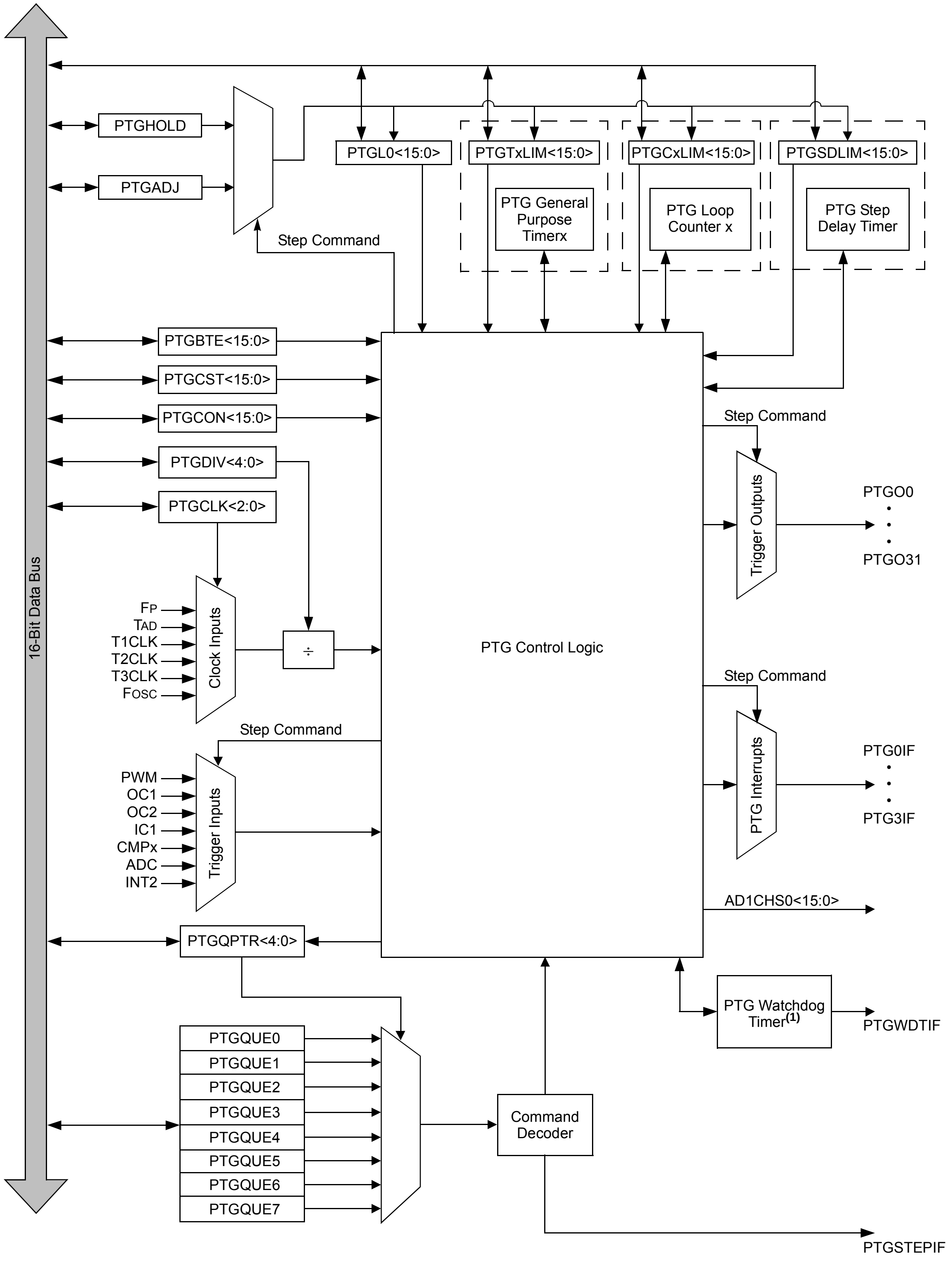
2: Channels 1, 2 and 3 are not applicable for the 12-bit mode of operation.

3: These bits can be updated with Step commands from the PTG module. See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for more information.

4: When ADDMAEN (AD1CON4<8>) = `1`, enabling DMA, only ADC1BUF0 is used.

5: OA3 is not available for 28-pin devices.

FIGURE 24-1: PTG BLOCK DIAGRAM



Note 1: This is a dedicated Watchdog Timer for the PTG module and is independent of the device Watchdog Timer.

REGISTER 25-3: CM4CON: COMPARATOR 4 CONTROL REGISTER (CONTINUED)

bit 5	**Unimplemented:** Read as '`0`'
bit 4	**CREF:** Comparator Reference Select bit (VIN+ input)(1) `1` = VIN+ input connects to internal CVREFIN voltage `0` = VIN+ input connects to C4IN1+ pin
bit 3-2	**Unimplemented:** Read as '`0`'
bit 1-0	**CCH<1:0>:** Comparator Channel Select bits(1) `11` = VIN- input of comparator connects to OA3/AN6 `10` = VIN- input of comparator connects to OA2/AN0 `01` = VIN- input of comparator connects to OA1/AN3 `00` = VIN- input of comparator connects to C4IN1-

Note 1: Inputs that are selected and not available will be tied to VSS. See the **"Pin Diagrams"** section for available inputs for each package.

REGISTER 26-2: CRCCON2: CRC CONTROL REGISTER 2

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	DWIDTH4	DWIDTH3	DWIDTH2	DWIDTH1	DWIDTH0
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	PLEN4	PLEN3	PLEN2	PLEN1	PLEN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13	**Unimplemented:** Read as ‘0’
bit 12-8	**DWIDTH<4:0>:** Data Width Select bits These bits set the width of the data word (DWIDTH<4:0> + 1).
bit 7-5	**Unimplemented:** Read as ‘0’
bit 4-0	**PLEN<4:0>:** Polynomial Length Select bits These bits set the length of the polynomial (Polynomial Length = PLEN<4:0> + 1).

TABLE 30-45: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = `1`, CKP = `0`, SMP = `0`) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	Lesser of FP or 15	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS1}}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS1}}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SS1}}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	SDO1 Data Output Valid after $\overline{\text{SS1}}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-48: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = `0`, CKP = `0`, SMP = `0`) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**(1)	**Min.**	**Typ.**(2)	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS1}}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS1}}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{\text{SS1}}$ ↑ after SCK1 Edge	1.5 T_{CY} + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

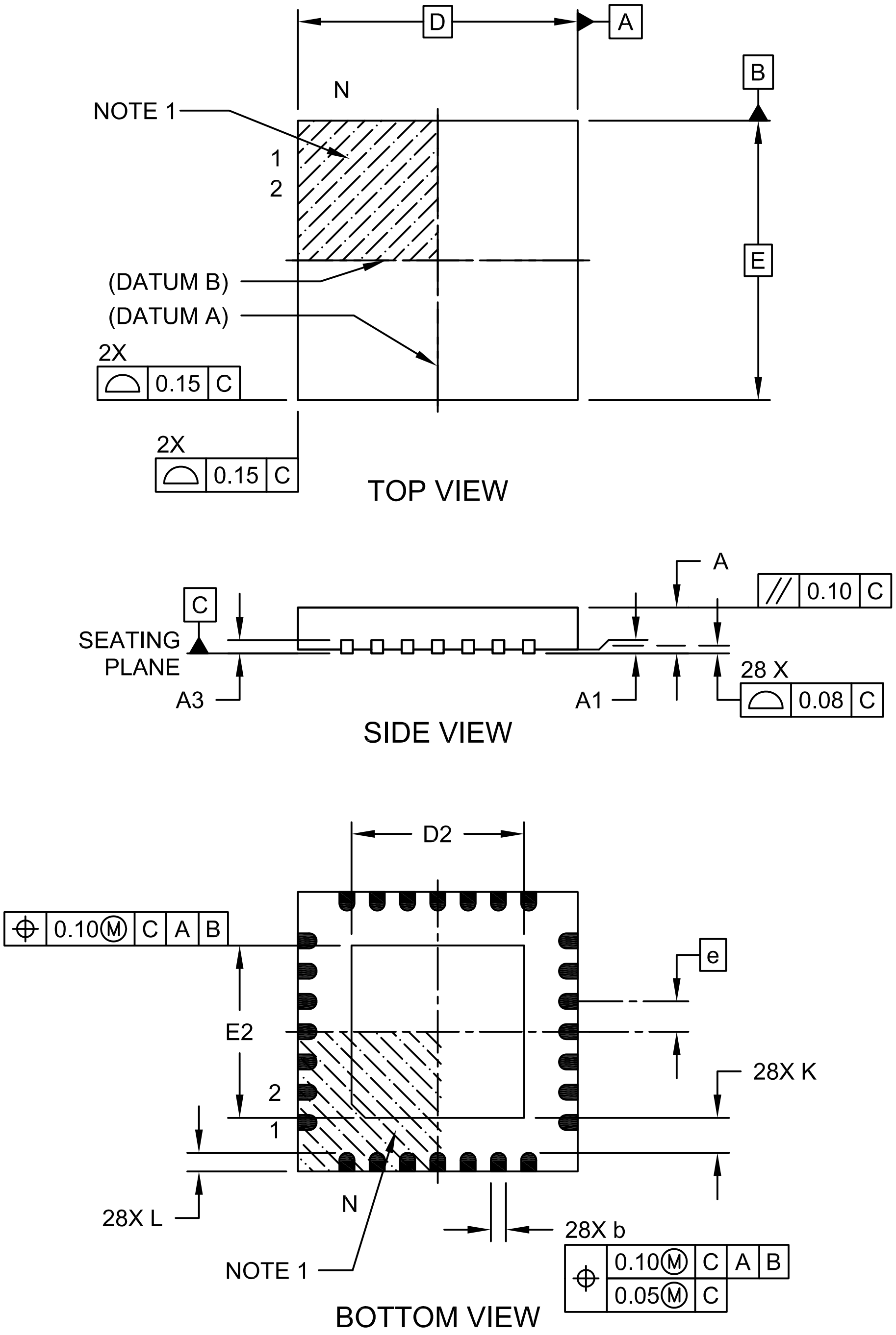
2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 91 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S] With 0.40 mm Terminal Length

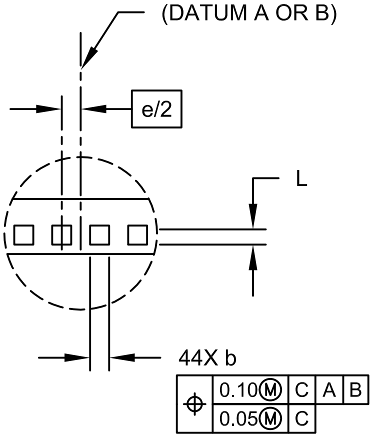
Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



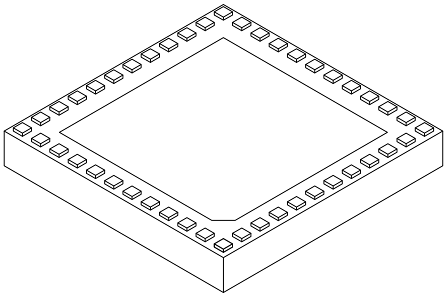
Microchip Technology Drawing C04-124C Sheet 1 of 2

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N	44		
Number of Pins per Side	ND	12		
Number of Pins per Side	NE	10		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E	6.00 BSC		
Exposed Pad Width	E2	4.40	4.55	4.70
Overall Length	D	6.00 BSC		
Exposed Pad Length	D2	4.40	4.55	4.70
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-157C Sheet 2 of 2

NOTES:

NOTES: